

# DUT Electronics

## 047 Coax Interconnect Cycling Test Results



11/24/2021

# Objective

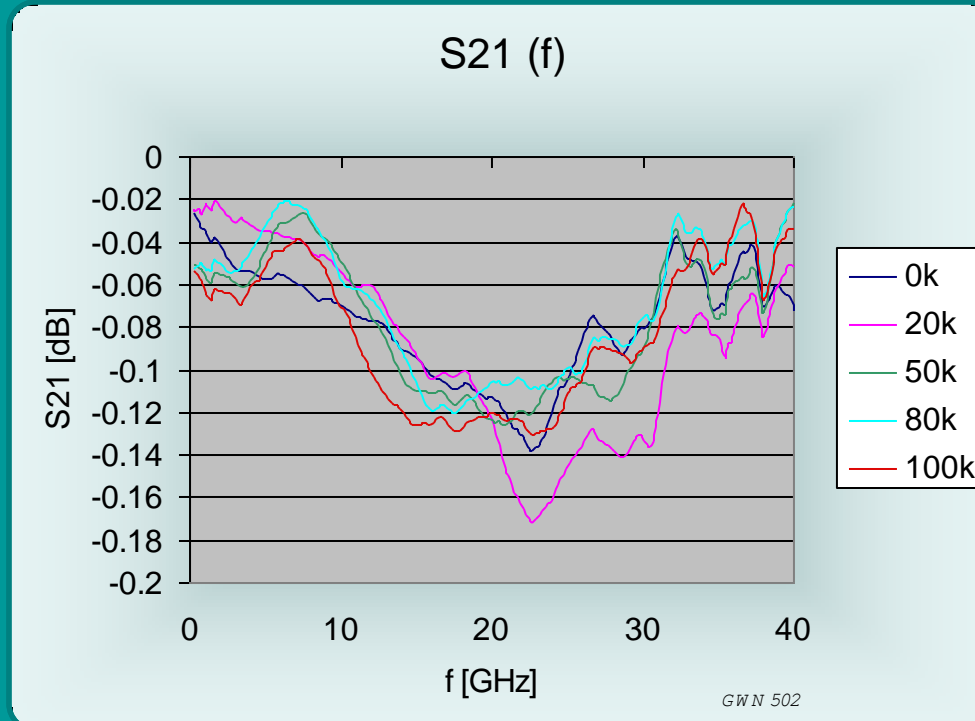
- Test socket
  - TDR
  - TDT
  - Insertion loss
  - Return loss
- Cycle mechanically to 100k

# Setup

- Agilent HP8722C VNA option 10
- 50 MHz-40.05 GHz
- Effective risetime  $\sim 25$  ps
- Custom DUT holder

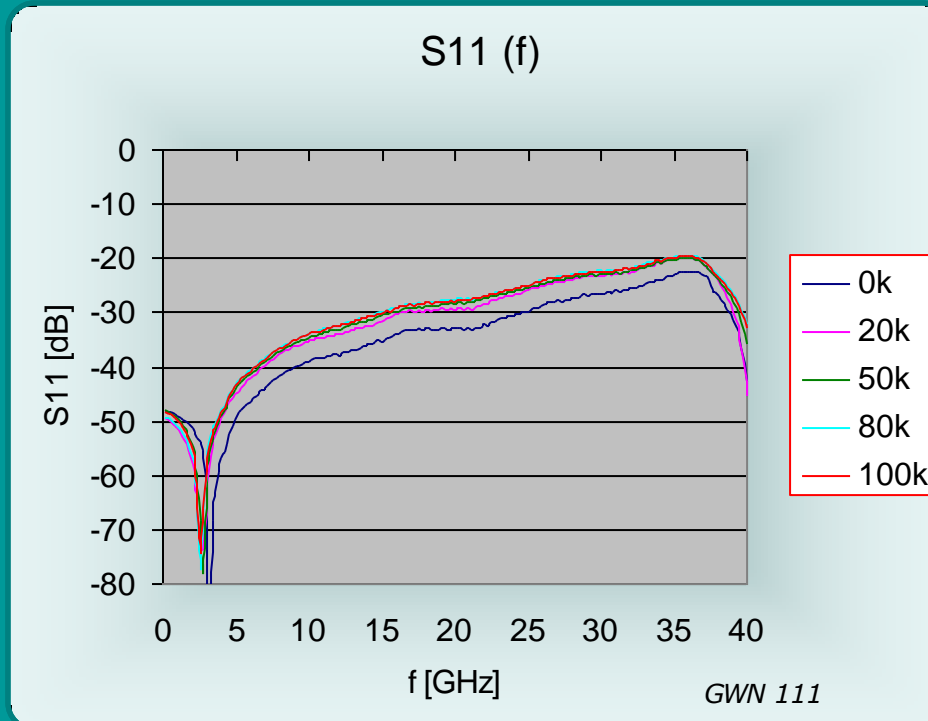


# Insertion loss



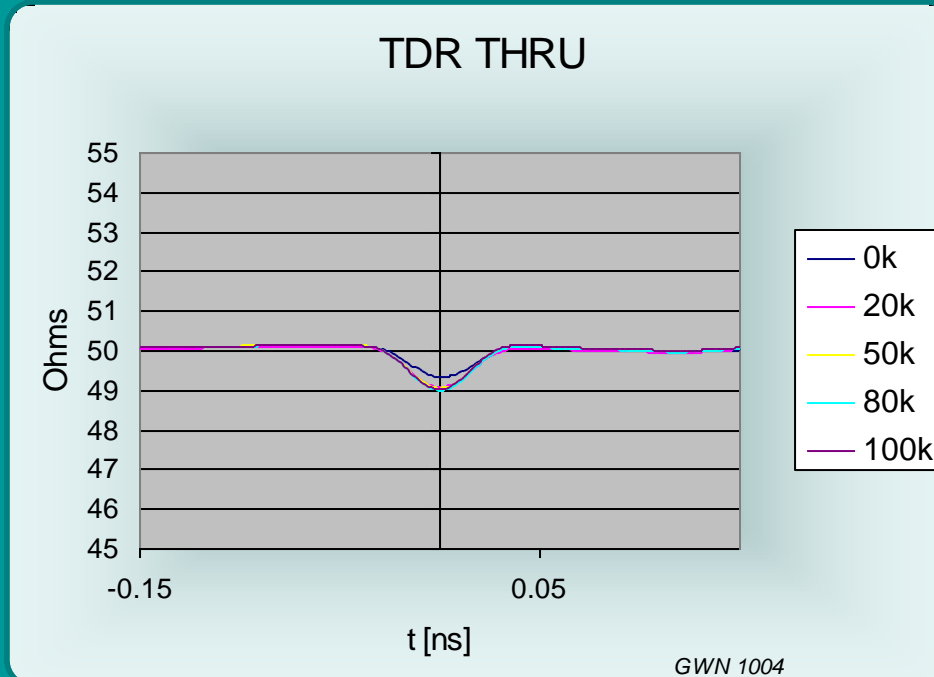
Some measurement to measurement variations must also be taken into account. Contributions may come from planarity and force of compression.

# Return loss



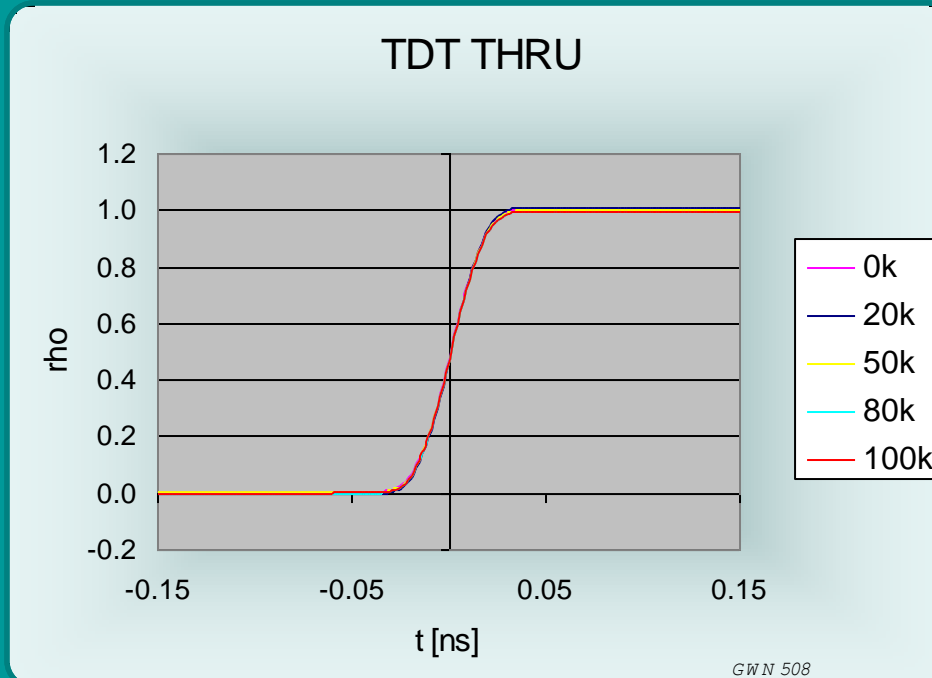
Some measurement to measurement variations must also be taken into account. Contributions may come from planarity and force of compression.

# TDR



Some measurement to measurement variations must also be taken into account. Contributions may come from planarity and force of compression.

# TDT



TDT is not affected noticeably by the small changes

# Summary

- Variations in electrical performance found during cycling are small.
- Au over Ni plated surfaces were used during cycling.
- After 100k cycles the sample showed almost no metallic deposits around the center conductor:

